



**Press Release**

## **Unisem Begins Volume Production of Packages Using Proprietary Copper Wirebonding Process**

**Kuala Lumpur, Malaysia – October 13, 2008** – [Unisem Group](#) today announced that it has started volume shipment of packages using its industry-leading copper wirebonding technology. Unisem's copper wirebond process has been qualified by several IC manufacturers worldwide, including [Integrated Device Technology](#) (IDT), a leading provider of mixed-signal semiconductor solutions. The IDT thin shrink small outline packages (TSSOP) integrate Unisem's copper wirebonds for a wide range of applications, including clock devices for desktops and notebook PCs.

Increased interest in copper wirebonding has been driven by the enhanced performance characteristics of copper, such as high tensile strength, thermal conductivity, lower electrical resistance and better performance during high-temperature storage tests. Products that integrate copper wirebonds have proven better electrical test yields than devices wirebonded with gold.

"In line with Unisem's goal of delivering advanced packaging solutions to meet the emerging technology requirements of customers, we have developed an innovative copper wirebond process that offers several advantages over gold," said Jean Ramos, chief technology officer at Unisem.

"IDT recognizes the traction copper has gained as an interconnect material in semiconductor packaging. The clear advantages of copper – better performance and higher electrical test yields – helped convince us and our customers of the strategic benefits we would receive by using copper wire," said Anne Katz, vice president of Worldwide Assembly and Test for IDT.

With customer demand for copper wirebonding increasing, 30 percent of Unisem's wirebonders will be set up for copper by 2009.

### **About Unisem**

Unisem is a global provider of semiconductor assembly and test services for many of the world's most successful electronics companies. Unisem offers an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding, a wide range of leadframe and substrate IC packaging, wafer level CSP and RF, analog, digital and mixed-signal test services. Our turnkey services include design, assembly, test, failure analysis, and electrical and thermal characterization. With approximately 9,500 employees

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worldwide, Unisem has factory locations in Ipoh, Malaysia; Wales, United Kingdom; Chengdu, People's Republic of China; Batam, Indonesia and Sunnyvale, USA. The company is headquartered in Kuala Lumpur, Malaysia. For more information about Unisem, please visit [www.unisemgroup.com](http://www.unisemgroup.com).

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